

iC-TW2 8-BIT SIN/COS INTERPOLATION IC WITH INTEGRATED EEPROM



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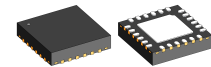
FEATURES

- Programmable angle resolution from 1 to 256 steps per period
- Interpolation factors from x0.25 to x64
- Input frequency to 115 kHz with x64, to 230 kHz with x32, to 460 kHz with x16
- Latency of less than 1 μ s
- Selectable gain permits single-ended and differential input signals from 10 mV to 1.5 V peak-peak
- Index gating input with fine adjustable offset
- Programmable index pulse output position and width
- Four incremental output modes: quadrature encoder with index, up/down clock, incr./direction, 3 phase commutation
- Programmable filter and hysteresis
- Direct sensor connection, minimized count of external components
- Non-volatile setup due to internal EEPROM
- Fully re-programmable via serial 1- and 2-wire interfaces
- Power-on reset circuit and on-chip oscillator
- ESD protection and TTL-/CMOS-compatible outputs
- Operation at 3.0 V to 5.5 V, from -40 °C to +125 °C

APPLICATIONS

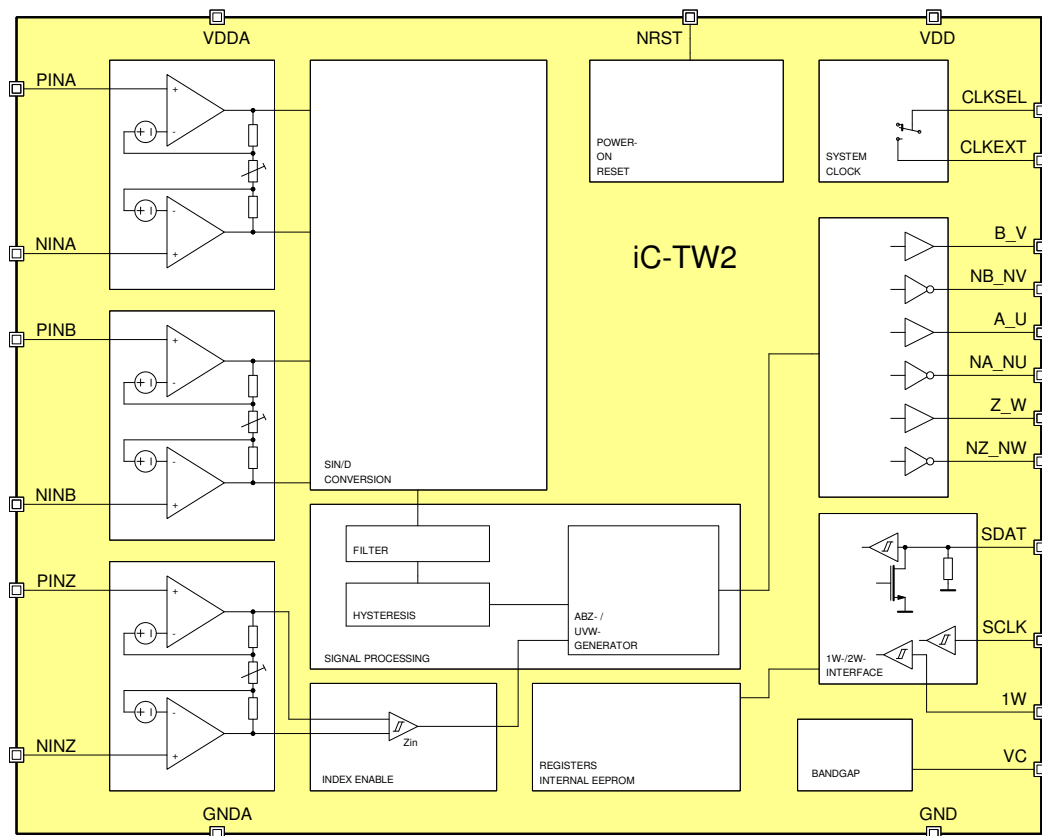
- Interpolation IC for position data acquisition from analog sine/cosine sensors
- Optical linear and rotary encoders
- Magneto resistive sensors and encoders

PACKAGES



QFN24 (4 mm x 4 mm)

BLOCK DIAGRAM



DESCRIPTION

iC-TW2's interpolation engine accepts two fully differential sensor bridges delivering sine and cosine input signals to produce a highly interpolated output signal. No further external components are required. Single-ended sensor signals are supported by tying the negative input terminals to the signal reference, usually VDD/2.

iC-TW2 generates one index pulse for every input period. The position in respect to the start of the period as well as the width of the pulse is fully programmable.

There are four different output modes provided, including 3-phase commutation output for brushless DC motors. To meet requirements for a wide range of applications, iC-TW2 is highly programmable.

Two serial interfaces have been included to permit configuration of the device, also accessing the internal EEPROM. Both interfaces allow complete configuration of the device including transfer of setup data to internal registers and the on-chip EEPROM for non-volatile storage.

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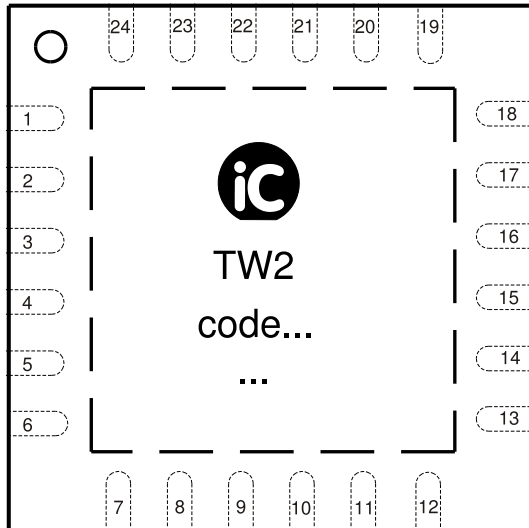
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PACKAGING INFORMATION

PIN CONFIGURATION QFN24 4 mm x 4 mm



PIN FUNCTIONS

No.	Name	Function
1	VDD	+3 V to +5.5 V Digital Supply Voltage
2	B_V	B Signal/V Signal Output
3	NB_NV	Inverted B/Inverted V Signal Output
4	A_U	A Signal/U Signal Output
5	NA_NU	Inverted A/Inverted U Signal Output
6	GND	Digital Ground
7	NZ_NW	Inverted Z/Inverted W Signal Output
8	Z_W	Z Signal/W Signal Output
9	1W	1W-Interface, signal input
10	VDDA	+3 V to +5.5 V Analog Supply Voltage
11	GNDA	Analog Ground
12	n.c.	Pin not connected
13	PINB	Signal Input B+
14	NINB	Signal Input B-
15	CLKSEL	System Clock Selection Input
16	NRST	External Reset Input (active low)
17	NINA	Signal Input A-
18	PINA	Signal Input A+
19	VC	1.2 V Reference Voltage Output
20	NINZ	Signal Input Z- (Index)
21	PINZ	Signal Input Z+ (Index)
22	SCLK	2-Wire Interface, clock input
23	CLKEXT	External Clock Input
24	SDAT	2-Wire Interface, serial data in/out
TP		Thermal Pad (bottom side)

The *Thermal Pad* of the QFN package (bottom side) is to be connected to a ground plane on the PCB which must have GND potential. GNDA must be wired to GND.

Only pin 1 marking on top or bottom defines the package orientation; label and lot codes can be subject to changes.

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ABSOLUTE MAXIMUM RATINGS

These ratings do not imply operating conditions; functional operation is not guaranteed. Beyond these ratings device damage may occur.

Item No.	Symbol	Parameter	Conditions	Limits		Unit
				Min.	Max.	
G001	VDD, VDDA	Voltage at VDD, VDDA	referenced to GND	-0.3	6.0	V
G002	Δ VDDA	Voltage Difference VDD vs. VDDA	Δ VDDA = VDD - VDDA	0	0.5	V
G003	V()	Voltage at PINA, NINA, PINB, NINB, PINZ, NINZ, B_V, NB_V, A_U, NA_U, Z_W, NZ_W, 1W, SDAT, SCLK, CLKSEL, CLKEXT	referenced to GND	-0.3	VDD + 0.5 V	V
G004	I()	Current in PINA, NINA, PINB, NINB, PINZ, NINZ, B_V, NB_V, A_U, NA_U, Z_W, NZ_W, 1W, SDAT, SCLK, CLKSEL, CLKEXT, VC		-20	20	mA
G005	Vd	ESD Susceptibility Of Signal Outputs	HBM, 100 pF discharged through 1.5 k Ω ; pins A_U, NA_U, B_V, NB_V, Z_W, NZ_W		1.5	kV
G006	Vd	ESD Susceptibility (remaining pins)	HBM, 100 pF discharged through 1.5 k Ω		1	kV
G007	Tj	Junction Temperature		-40	125	$^{\circ}$ C
G008	Ts	Storage Temperature		-40	125	$^{\circ}$ C

THERMAL DATA

Item No.	Symbol	Parameter	Conditions	Limits			Unit
				Min.	Typ.	Max.	
T01	Ta	Operating Ambient Temperature		-40		125	$^{\circ}$ C
T02	Rthja	Thermal Resistance Chip To Ambient	QFN24 surface mounted to PCB, following JEDEC 51		32		K/W

All voltages are referenced to ground unless otherwise stated.

All currents flowing into the device pins are positive; all currents flowing out of the device pins are negative.

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ELECTRICAL CHARACTERISTICS

Operating conditions: VDD = VDDA = 3.0...5.5 V, Tj = -40...125 °C, unless otherwise stated

Item No.	Symbol	Parameter	Conditions				Unit
				Min.	Typ.	Max.	
Total Device							
001	VDD, VDDA	Permissible Supply Voltage VDD, VDDA		3.0		5.5	V
002	I(VDD, VDDA)	Total Supply Current	VDD = 3.3 V at 0 Hz VDD = 3.3 V at 100 kHz VDD = 5.5 V at 0 Hz VDD = 5.5 V at 100 kHz			5 20 8 40	mA mA mA mA
003	Vc()hi	Clamp-Voltage hi at all pins	Vc()hi = V() - VDD; I() = 10 mA	0.5		1.3	V
004	Vc()lo	Clamp-Voltage lo at all pins	I() = -10 mA	-1.3		-0.3	V
Input Amplifier PINA, NINA, PINB, NINB							
101	Vin()sig	Permissible Input Voltage Range		1.4		VDD - 1.2	V
102	Step(GC)	Nominal Coarse Gain Step Size			6.0		dB
103	AGabs(GC)	Coarse Gain Absolute Accuracy		-1.0		3.5	dB
104	Step(GF)	Nominal Fine Gain Step Size			0.7		dB
105	AGabs(GF)	Fine Gain Absolute Accuracy		-0.3		0.3	dB
106	CGM	Gain Matching G(CHA)/G(CHB)		0.85		1.15	
107	Vin()os	Input Referred Offset Voltage		-15		15	mV
108	Vout()ossc	Output Referred Offset Correction Step Accuracy		-10		10	mV
109	Step(OFSx)	Nominal Offset Correction Step Size			13		mV
110	Vout()os	Output Referred Offset Voltage		-40		40	mV
111	FR	Permissible Input Frequency; Frequency Ratio FR = f _{cal} / f _{in}	INTER = 1 ... 64, FREQ = 0 INTER = 1 ... 64, FREQ = 1 INTER = 1 ... 64, FREQ = 2 ... 127 INTER = 65 ... 128, FREQ = 0 INTER = 65 ... 128, FREQ = 1 ... 127 INTER = 129 ... 255 INTER = 0	64 128 256 128 256 256 256			
Oscillator							
201	f _{cal}	Permissible User Calibrated Oscillator Frequency	measured at pin A_U in calib mode 2 as 1/32; VDD = 3.6 V, Tj = 25 °C VDD = 5.5 V, Tj = 25 °C			25 30	MHz MHz
202	f _{osc}	Oscillator Frequency	VDD = 3.0 V, Tj = 25 °C, CLOCK = 0 VDD = 3.0 V, Tj = 25 °C, CLOCK = 31 VDD = 5.5 V, Tj = 25 °C, CLOCK = 0 VDD = 5.5 V, Tj = 25 °C, CLOCK = 31	35 40		25 28	MHz MHz MHz MHz
203	TC _{osc}	Oscillator Frequency Temperature Drift	VDD = 5.0 V +/- 2 %		-0.12	0	%/K
204	VC _{osc}	Oscillator Frequency Power Supply Dependency	Tj = 25 °C		10		%/V
205	df _{osc}	Osc. Frequency Variation 3.3 V	supply voltage 3.3 V +/- 10%, Tj = 25 °C		+/-3		%
206	df _{osc}	Osc. Frequency Variation 5 V	supply voltage 5 V +/- 10%, Tj = 25 °C		+/-2		%
EEPROM							
301	Tret	Data Retention Time	Tj = 125 °C Tj = 85 °C	10 100			years years
302	Ncycles	Number of Erase/Write Cycles	Tj = 25 °C	1000			
303	Nread	Number of Read Cycles		10 ⁶			
Reference Voltage Output VC							
401	Vref(VC)	Reference Voltage	C _L = 100 nF, I(VC) = 0 mA	1.15	1.21	1.27	V

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ELECTRICAL CHARACTERISTICS

Operating conditions: VDD = VDDA = 3.0...5.5 V, Tj = -40...125 °C, unless otherwise stated

Item No.	Symbol	Parameter	Conditions				Unit
				Min.	Typ.	Max.	
Digital Inputs NRST							
501	Vt()hi	Input Threshold Voltage hi	VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%	1.5 3.3			V V
502	Vt()lo	Input Threshold Voltage lo	VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%			0.8 1.0	V V
503	Ipu()	Input Pull-up Current	V() = 0...VDD - 1 V			-3	µA
504	Vpu()	Input Pull-up Voltage	Vpu() = VDD - V(), I() = -3 µA			500	mV
Digital Inputs CLKSEL, CLKEXT							
601	Vt()hi	Input Threshold Voltage hi	VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%	1.5 3.3			V V
602	Vt()lo	Input Threshold Voltage lo	VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%			0.8 1.0	V V
603	Ipd()	Input Pull-down Current	V() = 1 V...VDD	4			µA
604	Vpd()	Input Pull-down Voltage	I() = 3 µA			500	mV
Digital Outputs A_U, NA_NU, B_V, NB_NV, Z_W, NZ_NW							
701	Vs()hi	Output Saturation Voltage hi	Vs()hi = V(VDD) - V(), I() = -6 mA; VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%			0.5 0.4	V V
702	Isc()hi	Short-circuit Current hi	V() = GND	-100		-15	mA
703	Vs()lo	Output Saturation Voltage lo	I() = 6 mA; VDD = 3.3 V +/- 10% VDD = 5.0 V +/- 10%			0.3 0.25	V V
704	Isc()lo	Short-circuit Current lo	V() = VDD	20		140	mA
705	tr()	Output Rise time	VDD = 3.0 V, CL() = 10 pF			4	ns
706	tf()	Output Fall Time	VDD = 3.0 V, CL() = 10 pF			4	ns
707	I()max	Permissible Load Current	source and sink	-10		10	mA
708	twhi	Duty Cycle at Output A, B	referred to period T, see Fig. 1		50		%
709	tAB	Output Phase A vs. B	referred to period T, see Fig. 1		25		%
710	tMTD	Minimum Transition Distance	see Fig. 1		1/f _{core}		
Signal Processing							
801	AAabs	Absolute Angular Accuracy	referred to 360° input signal GC(2:0) = 1 INTER(7:0) = 0 FREQ(6:0) = 127 f() < 50 Hz	-6		6	DEG
802	AArel	Relative Angular Accuracy	referred to period of A, B GC(2:0) = 1 INTER(7:0) = 0 FREQ(6:0) = 127 f() < 50 Hz	-20		20	%
803	ABrel	Relative Angular Accuracy A vs. B			1/2 AArel		%
Index Comparator PINZ, NINZ							
901	Vin()sig	Permissible Input Voltage Range		0.0		VDD	V
902	Vin()os	Input Referred Offset Voltage		-15		+15	mV
903	Vin()step	Comparator Offset Step Size	OFSZ = 0..7 OFSZ = 8..15		1.5 -1.5		mV mV
Power-Down-Reset							
A01	VDDon	Turn-on Threshold VDD (power on release)			1.8		V
A02	tbusy()cfg	Duration of Startup Configuration			20		ms

ELECTRICAL CHARACTERISTICS

Operating conditions: $V_{DD} = V_{DDA} = 3.0 \dots 5.5 \text{ V}$, $T_j = -40 \dots 125 \text{ }^\circ\text{C}$, unless otherwise stated

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
2-Wire Interface SDAT, SCLK							
B01	Vt()hi	Input Threshold Voltage hi	$V_{DD} = 3.3 \text{ V} \pm 10\%$ $V_{DD} = 5.0 \text{ V} \pm 10\%$	1.5 3.3			V V
B02	Vt()lo	Input Threshold Voltage lo	$V_{DD} = 3.3 \text{ V} \pm 10\%$ $V_{DD} = 5.0 \text{ V} \pm 10\%$			0.8 1.0	V V
B03	Ipd()	Input Pull-down Current	$V() = 1 \text{ V} \dots V_{DD}$	4			μA
B04	Vpd()	Input Pull-down Voltage	$I() = 3 \mu\text{A}$			500	mV
B05	Vs()lo	Saturation Voltage lo at SDAT	$I() = 2 \text{ mA}$			450	mV
B06	Vs()hi	Saturation Voltage hi at SDAT	$Vs()_{hi} = V_{DD} - V(); I() = -2 \text{ mA}$			700	mV
B07	Isc()lo	Short-circuit Current lo at SDAT		3			mA
B08	Isc()hi	Short-circuit Current hi at SDAT				-2.5	mA
B09	fclk(SCLK)	Permissible Clock Frequency SCLK	scales with oscillator frequency timing, see Table 32			1.25	MHz
B10	tbusy(e2p)	Max. Duration of EEPROM access	scales with oscillator frequency timing, see Table 32			20	ms
1-Wire Interface 1W							
C01	Vt()hi	Input Threshold Voltage hi	$V_{DD} = 3.3 \text{ V} \pm 10\%$ $V_{DD} = 5.0 \text{ V} \pm 10\%$	1.5 3.3			V V
C02	Vt()lo	Input Threshold Voltage lo	$V_{DD} = 3.3 \text{ V} \pm 10\%$ $V_{DD} = 5.0 \text{ V} \pm 10\%$			0.8 1.0	V V
C03	Ipu()	Input Pull-up Current	$V() = 0 \dots V_{DD} - 1 \text{ V}$			-3	μA
C04	Vpu()	Input Pull-up Voltage	$V_{pu}() = V_{DD} - V(), I() = -3 \mu\text{A}$			500	mV

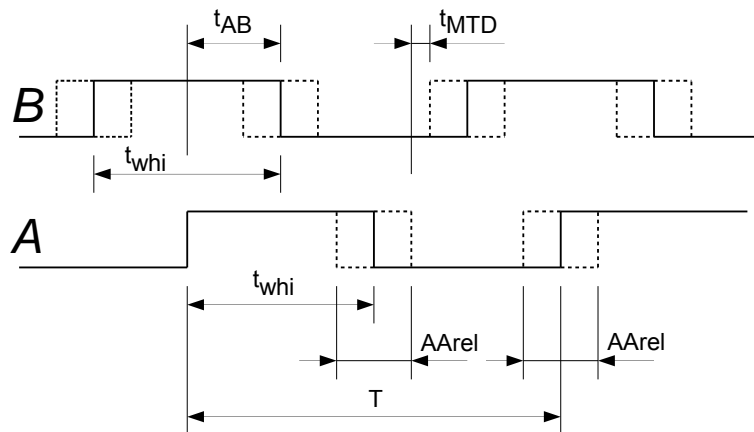


Figure 1: Relative phase distance

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REGISTER MAP

Register Map									
Addr	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Device Identification									
0x00	IDA(3:0)			IDB(3:0)					
Operating Modes									
0x01		RESET (P. 19)	CALIB1 (P. 16)	STARTUP(1:0)(P. 19)		DIR (P. 12)	MODE(1:0)(P. 12)		
Interpolation Rate									
0x02	INTER(7:0)(P. 12)								
Index Position									
0x03	IPOS(7:0)(P. 13)								
Index Width									
0x04	IWIDTH(7:0)(P. 13)								
Conversion Settings									
0x05	GRANULAR (P. 25)	FREQ(6:0)(P. 17)							
0x06					FILTER(1:0)(P. 17)		HYST(1:0)(P. 17)		
Gain and Offset									
0x07		GFB(1:0) (P. 11)		GFA(1:0) (P. 11)		GC(2:0) (P. 11)			
0x08		OFSA(5:0)(P. 11)							
0x09		OFBS(5:0)(P. 11)							
Bias and Oscillator Trimming									
0x0A		VC(1:0)(P. 25)		CLOCK(4:0)(P. 16)					
Index Computation and Miscellaneous									
0x0B	OFSZ(3:0)(P. 16)			EN_MON (P. 25)	CLKDLY (P. 25)	CLKDIV (P. 17)	CLKMODE (P. 25)		
Reserved and Calibration									
0x0C	Reserved(P. 25)							CALIB2	
0x0D	Reserved(P. 25)								
EEPROM Control									
0x0E	EE_READ (P. 25)	EE_WRITE (P. 24)	Reserved(P. 25)						
Test Register									
0x0F	MONITOR(7:0)(P. 25)								

Table 4: Register Map

PROGRAMMING

Input Stage	Page 11	Device Identification	Page 18
GC:	Coarse gain control (P. 11)	IDA:	Major Device Revision (P. 18)
GFA/B:	Fine gain control on channel A/B (P. 11)	IDB:	Minor Device Revision (P. 18)
OFSA/B:	Offset control on channel A/B (P. 11)		
Output Modes	Page 12	Start Up	Page 19
MODE:	Output mode selection (P. 12)	STARTUP:	Startup sequence selection (P. 19)
DIR:	Count direction (P. 12)	RESET:	Restart interpolation engine (P. 19)
INTER:	Interpolation rate selection (P. 12)		
IPOS:	Index pulse position (P. 13)	1W-/2-W-Interface And EEPROM Access .	Page 20
IWIDTH:	Index pulse width selection (P. 13)	EE_WRITE:	EEPROM store command (P. 24)
Index Gating	Page 15	Test Modes	Page 25
Calibration	Page 16	GRANULAR:	A/B output edge granularity control (P. 25)
CALIB1:	Calibration mode 1 select (P. 16)	VC:	Reference voltage fine tuning (P. 25)
CALIB2:	Calibration mode 2 select (P. 16)	CLKMODE:	Clock source selection (P. 25)
OFSZ:	Index comparator offset control (P. 16)	CLKDLY:	Clock distribution delay line selection (P. 25)
CLOCK:	Oscillator tune (P. 16)	EN_MON:	Position data monitor control (P. 25)
Configuration Dependencies	Page 17	MONITOR:	Monitor register (P. 25)
FREQ:	Maximum input frequency (P. 17)	EE_READ:	EEPROM read command (P. 25)
CLKDIV:	Master clock divider (P. 17)		
HYST:	Hysteresis control (P. 17)		
FILTER:	Datapath filter control (P. 17)		

DESCRIPTION OF INTERPOLATION

iC-TW2 is a monolithic A/D converter which converts sine/cosine sensor signals with a selectable resolution and hysteresis into angle position data. The interpolation function is shown in Figure 2.

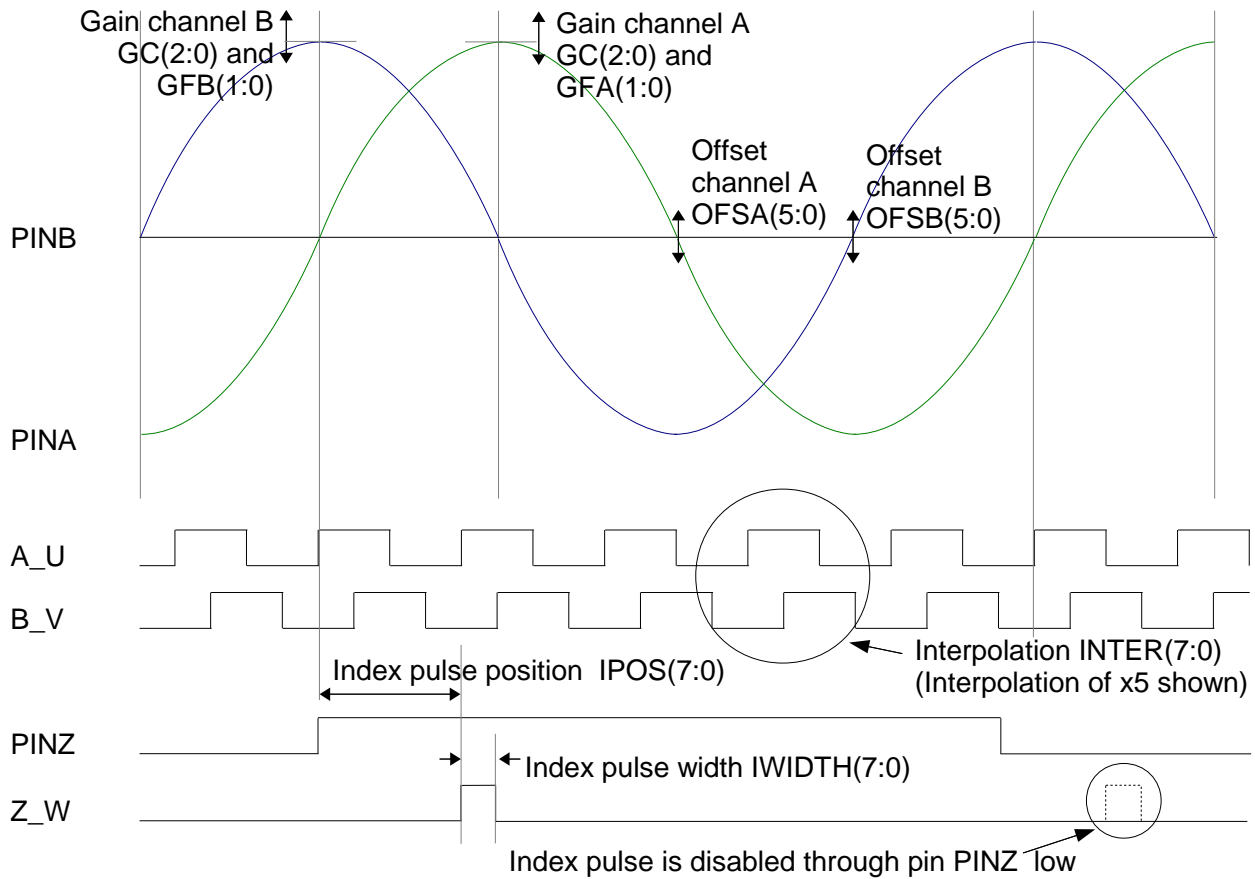


Figure 2: Interpolation function

Interpolation vs. Resolution

There is a difference between interpolation factor and resolution. Resolution (interpolation rate) is determined by the sum of edges at the incremental outputs (AB quadrature output) within one input signal period .

Dividing the resolution by the existing edges of the sine and cosine signals (=4) equals to the interpola-

tion factor. The interpolation factor equals to the the resolution divided by 4.

Example:

An interpolation factor of x8 brings a resolution of 32 (edges). To operate with an interpolation factor of 8 configure INTER(7:0) to 32.

INPUT STAGE

Programmable Gain Amplifier

A programmable gain amplifier (PGA) with output referred offset adjustment is used as input stage, shown in Figure 3. The coarse gain is common for both channel A and B and is programmed through register GC(2:0).

Fine tuning gain is applied individually to channel A and B by programming registers GFA(1:0) and GFB(1:0) respectively.

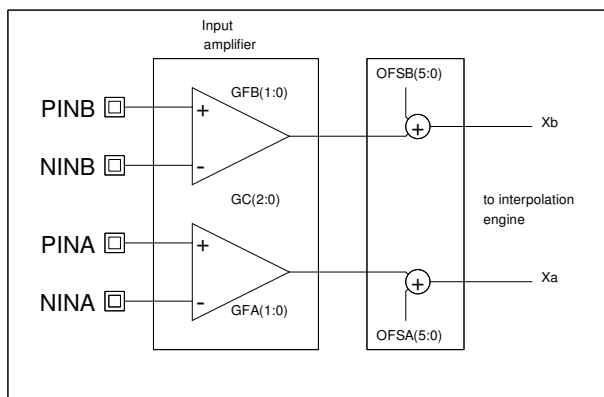


Figure 3: Input stage

GC(2:0)	Addr. 0x07; bit 2:0	R/W
Code	Input Signal Range $V_{IN\ peak-peak}$ [$V_{IN\ peak-peak\ diff.}$]	
000	400 mV - 750 mV [800 mV - 1.5 V] 400 mV max. @VDD = 3.0 V	
001	200 mV - 400 mV	
010	100 mV - 200 mV	
011	50 mV - 100 mV	
100	25 mV - 50 mV	
101	12.5 mV - 25 mV	
110	5 mV - 12.5 mV	
111	not defined (defaults to eeprom setting)	

Table 5: Coarse gain control of channel A/B

GFA(1:0)	Addr. 0x07; bit 4:3	R/W
GFB(1:0)	Addr. 0x07; bit 6:5	R/W
Code	Fine Gain (defaults to eeprom setting)	
00	0 dB	
01	0.7 dB	
10	1.4 dB	
11	2.1 dB	

Table 6: Fine gain control of channel A/B

Offset Adjustment

Offset adjustment is provided at the output of the input amplifier. It is individually programmed through register OFSA(5:0) and OFSB(5:0). Adjustment is made in steps of 13 mV and the corresponding register values

are sign magnitude encoded. Input referred offset becomes gain dependent and is defined as follows:

$$V_{OFS(A\ input\ referred)} = \frac{13\ mV * OFSA(5:0)}{GC(2:0)}$$

OFSA(5:0)	Addr. 0x08; bit 5:0	R/W
OFSB(5:0)	Addr. 0x09; bit 5:0	R/W
Code	Offset Correction (defaults to eeprom setting)	
111111	maximum negative adjust: -403 mV	
111110	-390 mV	
100001	-13 mV	
100000	no correction	
000000	no correction	
000001	13 mV	
011110	390 mV	
011111	maximum positive adjust: 403 mV	

Table 7: Offset control of channel A/B

Consider Table 8 regarding the relationship between coarse gain, permissible peak-to-peak input amplitude and the resulting offset correction range.

Coarse Gain GC(2:0)	Input Signal Range $V_{IN\ peak-peak}$	Input-referred offset corr. range $V_{OFS\ max}$	Input-ref. offset step dV_{OFS}
0	400 mV - 750 mV 400 mV max. @3 V	$\pm 806\ mV$	26 mV
1	200 mV - 400 mV	$\pm 403\ mV$	13 mV
2	100 mV - 200 mV	$\pm 202\ mV$	6.5 mV
3	50 mV - 100 mV	$\pm 101\ mV$	3.25 mV
4	25 mV - 50 mV	$\pm 50\ mV$	1.63 mV
5	12.5 mV - 25 mV	$\pm 25\ mV$	0.81 mV
6	5 mV - 12.5 mV	$\pm 12.6\ mV$	0.41 mV

Table 8: Input signal and offset correction ranges.

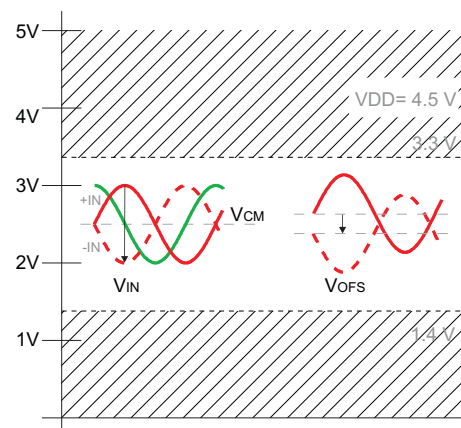


Figure 4: Permissible input voltage range at $V_{DD} = 5\ V \pm 10\ %$.

OUTPUT MODES

The iC-TW2 provides four different output modes, which are configured by programming bits MODE(1:0) of register 0x01. Modes 0, 1 and 2 are incremental modes whereas mode 3 is a 3-phase commutation output for brushless DC motors. Consider Figure 5 for a comparison of the 3 incremental output modes.

MODE(1:0)		Addr. 0x01; bit 1:0	R/W
Code	Function, <i>defaults to eeprom setting</i>		
00	AB quadrature (mode 0)		
01	up / dn (mode 1)		
10	inc / dir (mode 2)		
11	3 phase commutation (mode 3)		

Table 9: Output mode selection

In increment / direction mode the count direction can be inverted via control bit DIR of register 0x01.

DIR		Addr. 0x01; bit 2	R/W
Code	Function, <i>defaults to eeprom setting</i>		
0	Normal count direction		
1	Inverted count direction		

Table 10: Count direction selection

INTER (7:0)			
Adr 0x02, Bit 7:0 R/W			
Code	STEP Angle Steps Per Period	IPF Interpolation Factor	fin()max Max. Permissible Input Frequency *
0x00	256	64	115 kHz**
0x01	1	0.25	460 kHz
0x02	2	0.5	460 kHz
0x03	3	0.75	460 kHz
0x04	4	1	460 kHz
0x05	5	1.25	460 kHz
...	460 kHz
0x3C	60	15	460 kHz
0x3D	61	15.25	460 kHz
0x3E	62	15.5	460 kHz
0x3F	63	15.75	460 kHz
0x40	64	16	460 kHz
0x41	65	16.25	230 kHz
0x42	66	16.5	230 kHz
0x43	67	16.75	230 kHz
0x44	68	17	230 kHz
0x45	69	17.25	230 kHz
...	230 kHz
0x7C	124	31	230 kHz
0x7D	125	31.25	230 kHz
0x7E	126	31.5	230 kHz
0x7F	127	31.75	230 kHz
0x80	128	32	230 kHz
0x81	129	32.25	115 kHz
0x82	130	32.5	115 kHz
0x83	131	32.75	115 kHz
0x84	132	33	115 kHz
0x85	133	33.25	115 kHz
...	115 kHz
0xFA	250	62.5	115 kHz
0xFB	251	62.75	115 kHz
0xFC	252	63	115 kHz
0xFD	253	63.25	115 kHz
0xFE	254	63.5	115 kHz
0xFF	255	63.75	115 kHz
Notes	*) For $f_{osc} = 29.4 \text{ MHz}$, $FREQ = 0$, $CLKDIV = 0$. **) 115 kHz is fin()max for commutation operation (MODE = 3).		

Table 11: Converter resolution

AB Quadrature And Up/Down and Incr/Dir Modes

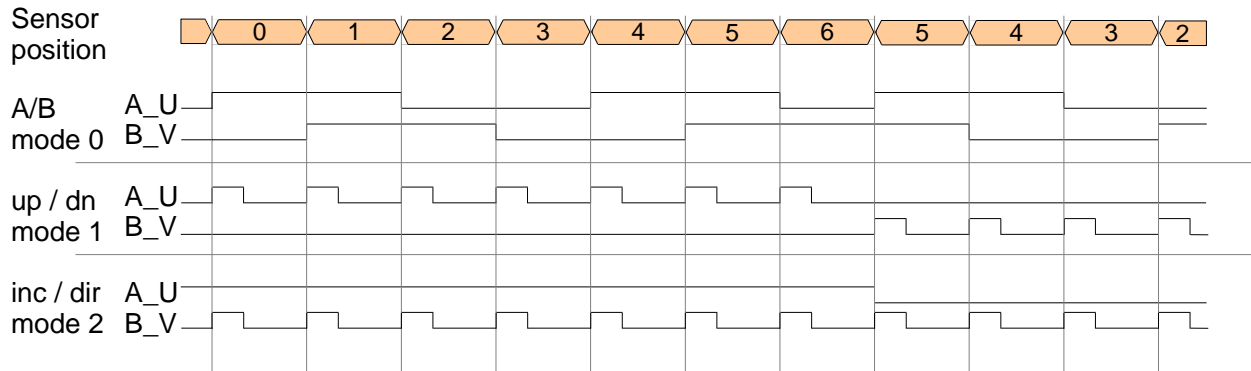


Figure 5: Incremental output modes (mode 0, 1, 2)

IPOS(7:0)		Addr. 0x03; bit 7:0	R/W
Code	Function, <i>defaults to eeprom setting</i>		
0	No offset		
1	1 increment offset		
2	2 increments offset		
...	...		
...	Index pulse will be shifted by IWIDTH(7:0) increments. Programmed value is within the range of 0 to INTER(7:0) - 1.		
...	...		
255	255 increments offset		
Note:	A fixed phase relation to A/B is guaranteed only with STARTUP(1:0) = 0b10 ("ABSOLUTE") or STARTUP(1:0) = 0b11 ("BURST").		

Table 12: Index pulse position

IWIDTH(7:0)		Addr. 0x04; bit 7:0	R/W
Code	Function, <i>defaults to eeprom setting</i>		
0	disable pulse generation		
1	1 increment width		
2	2 increments width		
...	...		
Any other value n	Index pulse will extend over IWIDTH(7:0) increments. Programmed value is within the range of 0 to INTER(7:0) - 1.		
...	...		
255	255 increments width		

Table 13: Index pulse width selection

3 Phase Commutation Mode

The 3 phase commutation output (mode 3) is shown in Figure 6. It is important that register INTER(7:0) is programmed with the value 0x00 in order for the commutation mode to work. The mode = 3 requires an internal interpolation INTER(7:0) of 256. Register IPOS(7:0) is used to accurately position the commutation. IWIDTH(7:4) and IWIDTH(3:0) is subsequently used to fine tune V and W in respect to U. All used offsets within the commutation mode (mode 3) as are IPOS(7:0), IWIDTH(3:0) and IWIDTH(7:4) operate in this step width of 1.4°. There is no other pole count commutation possible to configure as the described 3 phase commutation.

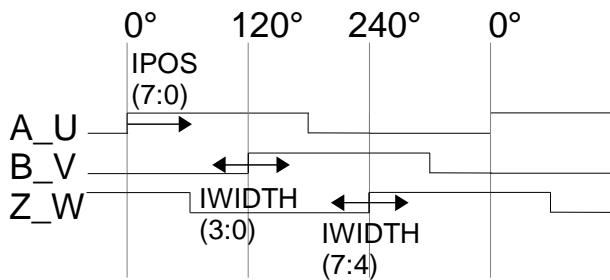


Figure 6: 3-Phase commutation output (mode 3)

IPOS(7:0)	Addr. 0x03; bit 7:0	R/W
Code	Function, <i>defaults to eeprom setting</i>	
0	0°	
1	1.40°	
2	2.81°	
...	...	
	Programmed value is within the range of 0 to INTER(7:0) - 1.	
...	...	
255	358,59°	

Table 14: UVW commutation signal position offset

IWIDTH(3:0)	Addr. 0x04; bit 3:0	R/W
Code	V output offset, <i>defaults to eeprom setting</i>	
0111	9.84°	
...	...	
0010	2.81°	
0001	1.40°	
0000	0°	
1111	-1.40°	
1110	-2.81°	
...	...	
1111	11.25°	

Table 15: V commutation signal position offset

IWIDTH(7:4)	Addr. 0x04; bit 7:4	R/W
Code	W output offset, <i>defaults to eeprom setting</i>	
0111	9.84°	
...	...	
0010	2.81°	
0001	1.40°	
0000	0°	
1111	-1.40°	
1110	-2.81°	
...	...	
1111	11.25°	

Table 16: W commutation signal position offset

INDEX GATING

The iC-TW2 can interface to a wide range of index gating sources. Most commonly used are the digital Hall sensor and the MR sensor bridge.

The digital Hall sensor provides a large swing input signal to the iC-TW2. Depending on the polarity of the Hall it is either connected to pin NINZ or PINZ. Most Hall sensors use an open drain stage pulling the output low in the presence of a magnetic field. The unused terminal PINZ or NINZ should be biased to an adequate mid voltage level to guarantee good noise margin. The iC-TW2 provides a constant 1.21 V at pin VC that can be used for this purpose (refer to Figure 7).

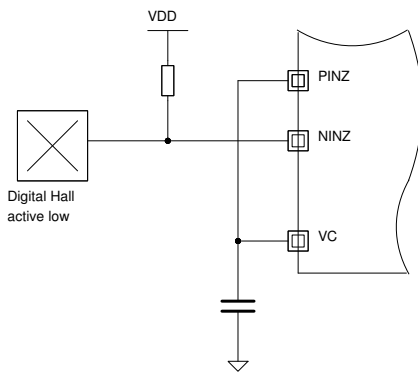


Figure 7: Digital Hall sensor index configuration

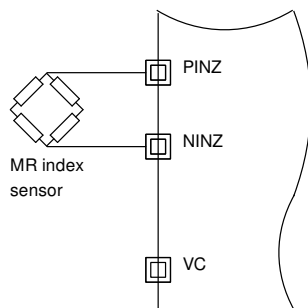


Figure 8: MR sensor index configuration

An MR sensor differential bridge can also be used to gate the index. Typically, the MR sensor provides a small signal amplitude. In addition, residual side lobes are present that can trigger double indexing. The iC-

TW2 provides offset control capability to fine tune the threshold voltage of the index comparator. This greatly simplifies end product calibration as variation in sensor offset can be compensated for.

Figure 9 shows a correctly set threshold when using an MR gating sensor. The side lobes are below the threshold line and no parasitic triggering occurs.

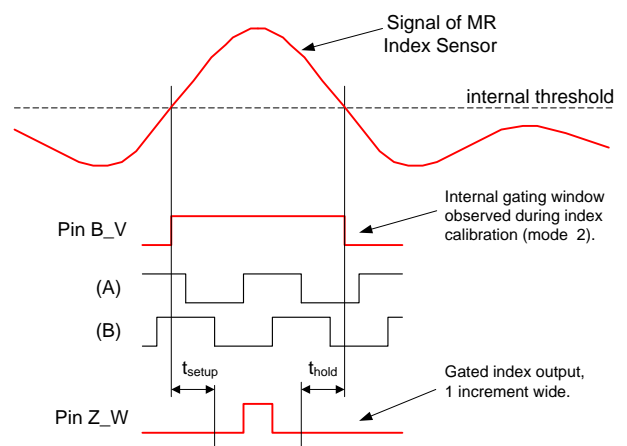


Figure 9: Index gating and calibration

Index gating should be calibrated at sine/cosine input frequencies below 5 kHz to minimize the effect of latency. Timings shown in Table 17 are valid for input frequencies below 5 kHz and f_{system} of 25 MHz. Once the timings are satisfied according to Table 17, correct operation is guaranteed up to the maximum input frequency as specified in Table 26 on page 18.

Parameter	Description	Condition *	min
t_{setup}	Index window setup time before rising edge of Z_W	no filter 8 average 16 average	0.4 μs 0.5 μs 0.7 μs
t_{hold}	Index window hold time after falling edge of Z_W	no filter 8 average 16 average	0.4 μs 0.5 μs 0.7 μs

*) According to register FILTER(1:0)
 $f_{\text{system}} = 25 \text{ MHz}$, all timings scale with f_{system} .
 Refer to Table 26 for more information

Table 17: Index gating and timing

CALIBRATION

In order to facilitate system gain and offset calibration, two calibration modes can be enabled by either setting bit CALIB1 of register 0x01 or CALIB2 of register 0x0C.

CALIB2	Addr. 0x0C; bit 0	R/W
CALIB1	Addr. 0x01; bit 5	R/W
CALIB2;1	Function, <i>defaults to eeprom setting</i>	
00	Normal operation, no calibration	
01	A/B gain and index calibration	
10	Oscillator and index window calibration	
11	Not permitted	

Table 18: Calibration modes

A/B gain and offset calibration

In calibration mode 1 the SIN/COS input is directly passed through two zero-cross comparators to output pin A and B respectively. In addition, the sum of the input signals

$$\frac{\text{SIN} + \text{COS}}{\sqrt{2}}$$

is also fed through a comparator and driven on pin Z.

The actual calibration process must be carried out in several steps.

1. Select proper coarse gain by programming register GC(2:0). Set GFA(1:0) and GFB(1:0) to 0.
2. Adjust offset register OFSA(5:0) and OFSB(5:0) until output A and B are 50% duty cycle.
3. Adjust fine gain register GFA(1:0) and GFB(1:0) until output Z is equidistant between output A and B.
4. Repeat step 1 and 2 until no more improvement can be achieved.

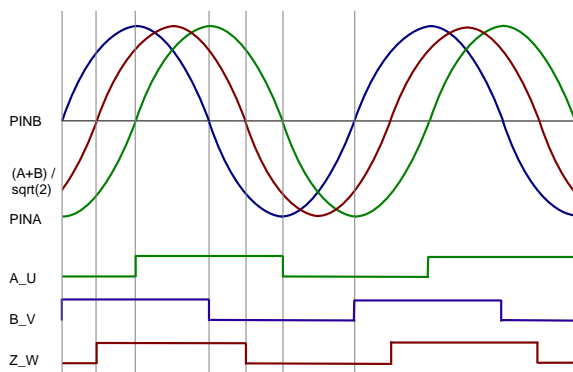


Figure 10: Output signals for A/B gain and offset adjustment in calibration mode 1.

Oscillator and index window calibration

When calibration mode 2 is enabled, the output of the index comparator is driven on pin B_V. In conjunction with the actual index output on pin Z_W, the gating window can be centered around the output pulse (see Figure 9). Fine offset adjustment applied to the input of the index comparator is possible through OFSZ(3:0) which is sign magnitude encoded. This is beneficial when using small amplitude index sources such as an MR sensor.

Simultaneously, the oscillator frequency $f_{\text{osc}}/32$ can be observed on pin A_U. Register CLOCK(4:0) is used to tune the oscillator to its desired frequency.

OFSZ(3:0)	Addr. 0x0B; bit 7:4	R/W
Code	Function, <i>defaults to eeprom setting</i>	
1111	maximum negative adjust, -10.5 mV	
1110	-9 mV	
1001	-1.5 mV	
...	...	
1000	no correction	
0000	no correction	
0001	1.5 mV	
...	...	
0110	9 mV	
0111	10.5 mV	
1	calibration mode 2 activated	

Table 19: Index comparator offset control

CLOCK(4:0)	Addr. 0x0A; bit 4:0	R/W
Code	Function, <i>defaults to eeprom setting</i>	
00000	Slowest clock	
...	...	
11111	fastest clock	

Table 20: Oscillator tuning

CONFIGURATION DEPENDENCIES

This section describes the dependencies between the chip configuration and the system's performance. It is vital to understand the implication of system parameters to be able to tune the iC-TW2 for full performance. It is especially important to correctly program register **FREQ(6:0)**, since this directly affects accuracy and maximum allowed input frequency.

Selecting configuration parameters

To select a proper configuration follow the outlined procedure below. Refer to Table 26 for reference.

1. Determine the maximum input frequency $f_{in(max)}$ as required by the application.
2. Calculate f_{core} based on $f_{in(max)}$ and resolution **INTER(7:0)**.
3. Select f_{system} based on the accuracy requirements. Accuracy is a function of resolution **INTER(7:0)** and clock scaling **FREQ(6:0)**. Always use the highest accuracy possible to still satisfy $f_{in(max)}$.
4. Determine f_{osc} . Selecting the slowest possible f_{osc} lowers power consumption and improves jitter performance.

Clock tuning

1. Observe $f_{osc}/32$ on pin **A_U** during calibration mode 2.
2. Use **CLOCK(4:0)** to tune the oscillator to the desired f_{cal} frequency. ($f_{pinA} = f_{osc}/32$)
3. Be aware that the oscillator can have as much as 20% frequency variation over the operating temperature range (-40 °C to 125 °C). The oscillator runs slower at higher temperatures. To guarantee performance at 125 °C it is necessary to tune the oscillator to typ. 12% higher frequency at room temperature of 25 °C.

Accuracy modes

The converter resolution **INTER(7:0)** in conjunction with the clock scaling **FREQ(6:0)** define iC-TW2's accuracy mode. Based on the selected accuracy mode other system parameters are defined as shown in Table 26.

INTER(7:0)	FREQ(6:0)	Accuracy Mode	Theoretical Absolute Accuracy
129 to 256; 0	0 to 127	High accuracy	±2.8°
65 to 128	0	Medium acc.	±5.6°
	1 to 127	High accuracy	±2.8°
1 to 64	0	Low accuracy	±11.2°
	1	Medium acc.	±5.6°
	2 to 127	High accuracy	±2.8°

Table 21: Accuracy modes

CLKDIV		Addr. 0x0B; bit 1	R/W
Code	Function (defaults to eeprom setting)		
0	$f_{system} = f_{osc}$		
1	$f_{system} = f_{osc} / 2$		
Note	It is recommended to use the divider when support for high input frequencies is not required.		

Table 22: Master clock divider

FREQ(6:0)		Addr. 0x05; bit 6:0	R/W
Code	Clock scaling (defaults to eeprom setting)		
0x00	$f_{core} = f_{system}$		
...	$f_{core} = f_{system} / (1 + \text{FREQ}(6:0))$		
0x7F	$f_{core} = f_{system} / 128$		

Table 23: Clock scaling

HYST(1:0)		Addr. 0x06; bit 1:0	R/W
Code	Function (defaults to eeprom setting)		
	<i>High accuracy</i>	<i>Medium / low accuracy</i>	
00	no hysteresis	no hysteresis	
01	±1.4°	±2.8°	
10	±2.81°	±5.6°	
11	±5.63°	±11.3°	

Table 24: Hysteresis control

FILTER(1:0)		Addr. 0x06; bit 3:2	R/W
Code	Function (defaults to eeprom setting)		
00	filter disabled		
01	Average of 8 samples		
10	Average of 16 samples		
11	undefined		
Notes	It is recommended to enable the filter in almost all cases as it removes loop instability noise. However, enabling the filter increases the Sin/Cos input to A/B output latency (see Table 26 for details).		

Table 25: Datapath filter control

iC-TW2 8-BIT SIN/COS INTERPOLATION IC WITH INTEGRATED EEPROM



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Description	Parameter	Requirement or relationship	Control bit
Oscillator Frequency Calibrated Osc. Frequ.	f_{osc} [Hz] f_{cal} [Hz]	< 30 MHz at VDD = 5.5 V, < 25 MHz at VDD = 3.6 V; see Elec. Char. item 201	CLOCK(4:0)
System Clock	f_{system} [Hz]	$f_{system} = f_{osc}$, if CLKDIV = 0 $f_{system} = f_{osc}/2$, if CLKDIV = 1	CLKDIV
Core Clock	f_{core} [Hz]	$f_{core} = f_{system} / (1 + \text{FREQ}(6:0))$	FREQ(6:0)
Front-end Frequency Limit*	f_{front} [Hz]	$f_{front} = f_{system} / 256$, if High Accuracy $f_{front} = f_{system} / 128$, if Medium Accuracy $f_{front} = f_{system} / 64$, if Low Accuracy f_{front} is the maximum sin/cos input frequency which can be processed by the front-end.	FREQ(6:0) INTER(7:0)
Back-end Frequency Limit*	f_{back} [Hz]	$f_{back} = f_{core} / \text{INTER}(7:0)$ f_{back} is the maximum sin/cos input frequency which can be processed by the A/B generator back-end.	INTER(7:0)
Max. Input Frequency	$f_{in()max}$ [Hz]	$f_{in()max} = \min(f_{front}, f_{back})$ The permissible max. sin/cos input frequency is determined by f_{back} or f_{front} , whatever means the lower limit.	
Max. A/B Output Frequency	$f_{out(AB)max}$ [Hz]	$f_{out(AB)max} = 1 / f_{core}$ $f_{out(AB)max} = 0.25 / t_{edge}$	
A/B Edge Separation, Min. Transition Distance	t_{edge} , t_{MTD}	$t_{edge} = t_{MTD} = 1 / f_{core}$	
A/B Edge Granularity	t_{gran}	$t_{gran} = 1 / f_{system}$	
Sin/Cos to A/B Output Latency	$t_{latency}$ [μ s]	10 / f_{system} [MHz] + 0.2, if no filter 18 / f_{system} [MHz] + 0.2, if 8 sample average 26 / f_{system} [MHz] + 0.2, if 16 sample average	FILTER(1:0)
*) Parameter does not represent a functional IC parameter, parameter introduced for calculation purposes only.			

Table 26: Configuration dependencies

DEVICE IDENTIFICATION

IDA(3:0)		Addr. 0x00; bit 7:4	R/W
Code	Function, Major device identification		
	Mask Programmed Value Identifies Major Revision		

Table 27: Major device revision

IDB(3:0)		Addr. 0x00; bit 3:0	R/W
Code	Function, Minor device identification		
	Mask Programmed Value Identifies Minor Revision		

Table 28: Minor device revision

START UP

Power-On-Reset

The iC-TW2 contains a built-in Power-On-Reset (POR) circuitry. The POR keeps the iC-TW2 in reset as long as the applied power supply voltage does not allow reliable operation. Once the power supply ramps up above 1.8 V, the POR releases the reset and the iC-TW2 starts the configuration cycle. 20 ms after the device goes out of reset, normal operation begins.

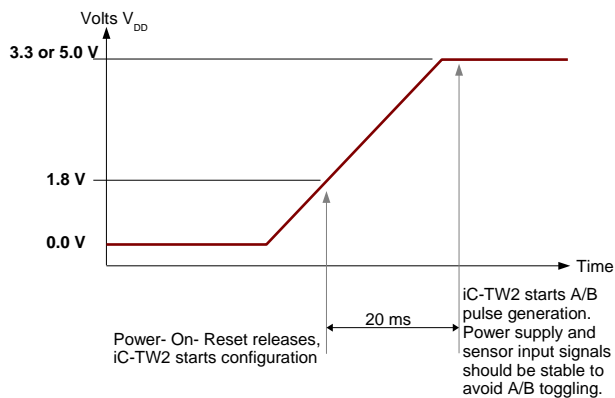


Figure 11: Power supply ramp-up

To avoid A/B output toggling it is important that the power supply and the input signals are stable as soon as normal operation begins. In applications with a slowly rising power supply, it might be necessary to connect an external RC reset to pin NRST to prolong the reset. In applications where startup A/B toggling is acceptable, no precaution must be taken as the iC-TW2 will properly power up on an indefinitely slow supply rise time.

The iC-TW2 startup behaviour is controlled by programming the two control bits STARTUP(1:0) in register 0x01. Three possible startup configurations are allowed, shown in Figure 12. The default behaviour must be specified by the eeprom.

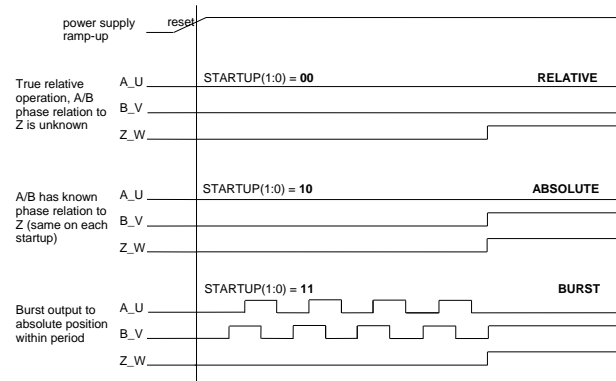


Figure 12: Startup behaviour

STARTUP(1:0)		Addr. 0x01; bit 4:3	R/W
Code	Function		
00	RELATIVE A/B output signals are kept low during startup. This resembles true relative operation since there is no relationship between A/B levels and sensor position (and therefore Z output) on startup.		
01	Reserved		
10	ABSOLUTE A/B output signals are phase-related to Z output. A/B output levels are defined by the absolute sensor position within a period. The register <i>IPOS</i> can be used to program the desired A/B to Z phase relationship.		
11	BURST The absolute sensor position within the period is output by an A/B burst.		

Table 29: Startup sequence selection

Reset

A control bit RESET is provided to block any burst A/B pulses during chip reconfiguration by a microcontroller. While RESET is set A/B/Z output generation is stopped. Access to the interface and register bank is not affected.

RESET		Addr. 0x01; bit 6	R/W
Code	Function		
0	A/B/Z output according to STARTUP default		
1	A/B/Z output halted following reset		
Notes	RESET = 1 may be programmed to the EEPROM or can be used temporarily to avoid spurious A/B/Z output pulses when reconfiguration by an external microcontroller is intended.		

Table 30: Restart of interpolation engine following power-on or software initiated reset.

1W-/2W-INTERFACE AND EEPROM ACCESS

Memory map

Figure 13 depicts the iC-TW2 memory map and interface diagram. A 2-wire read/write interface and a 1-wire write-only interface allow access to the register bank and the EEPROM bank. The register bank is 8 bits wide and it is used to control all chip functionality. Refer to section "Register Map" on page 8 for an overview of all registers.

NB: The 1W-Interface and the 2W-interface do not feature a timeout.

The EEPROM bank on the other hand is 32 bits wide. Address 0x05, 0x06 and 0x07 (3 * 4 bytes = 12 bytes) can be used to store user data such as product serial numbers, calibration and manufacturing information.

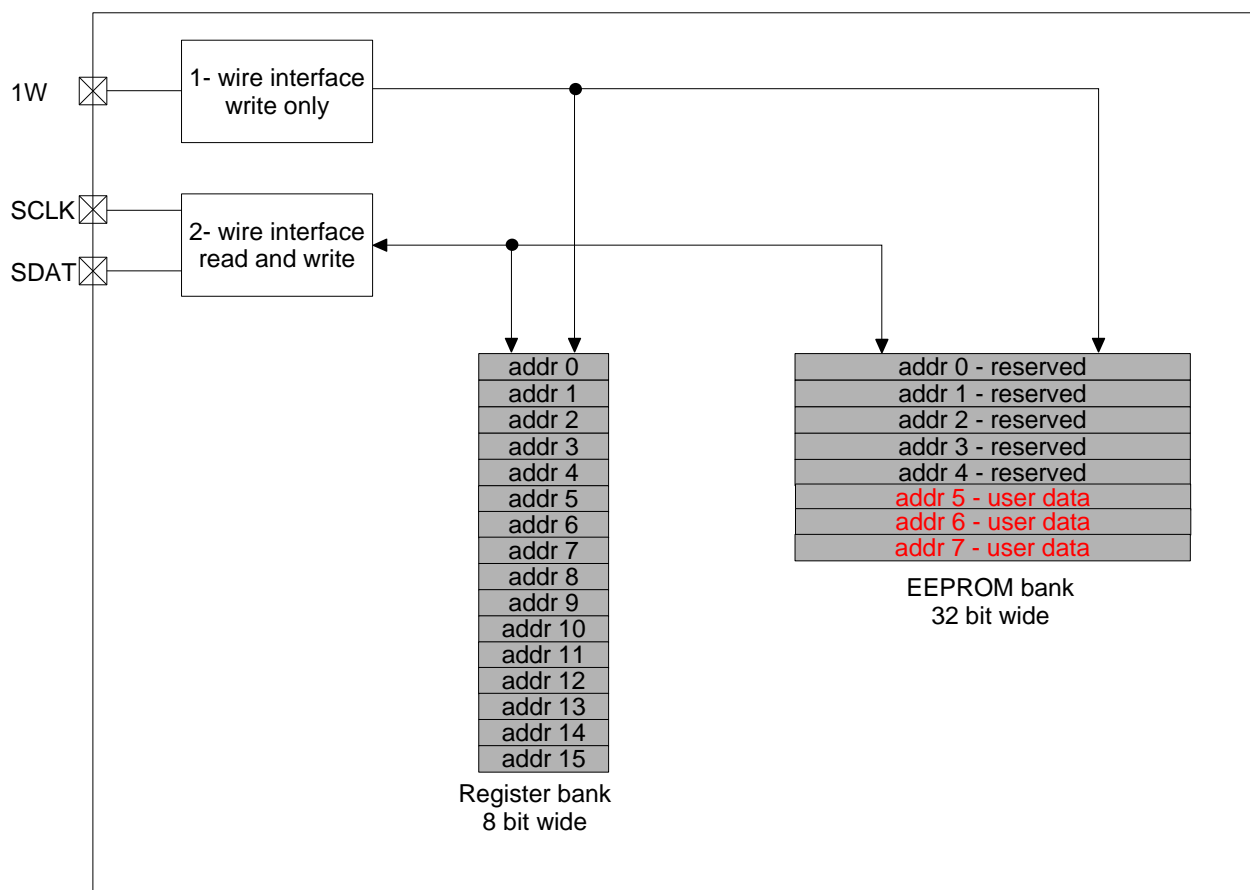


Figure 13: Memory map

2W-Interface

The first control interface is a standard 2-wire serial interface. It uses an external clock and bidirectional data line. It allows read and write access to all internal registers as well as access to the user EEPROM. The interface consists of two pins, a dedicated input SCLK, the shifting clock and SDAT for bidirectional serial data.

The interface handles four types of access requests:

1. Write to control register

2. Read from control register

3. Write to EEPROM register (including block access and erase)

4. Read from EEPROM register

Control register access is shown in Figure 14 (write) and Figure 15 (read) respectively. If SDAT is **00** after the start bit a write access is requested. The data word d(7:0) will be written into register a(4:0). Please note that a(4) is always 0 since the iC-TW2 only has 16 addressable registers.

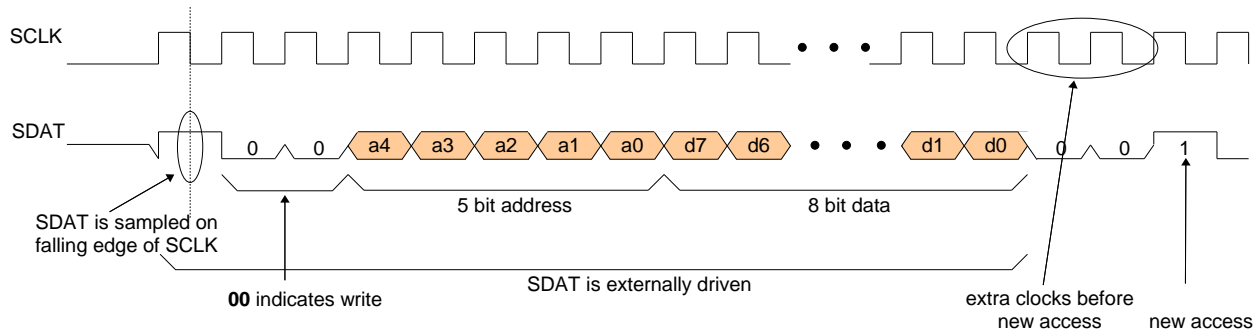


Figure 14: Register bank write access on 2W-Interface

On a register read access the register content is shifted out on SDAT. A read access is indicated by SDAT 10 after the start bit. There is an idle clock required between the last address bit a(0) and the first

data bit d(7) returned on SDAT. This clock cycle is used to avoid any bus contention while turning around the bus driver.

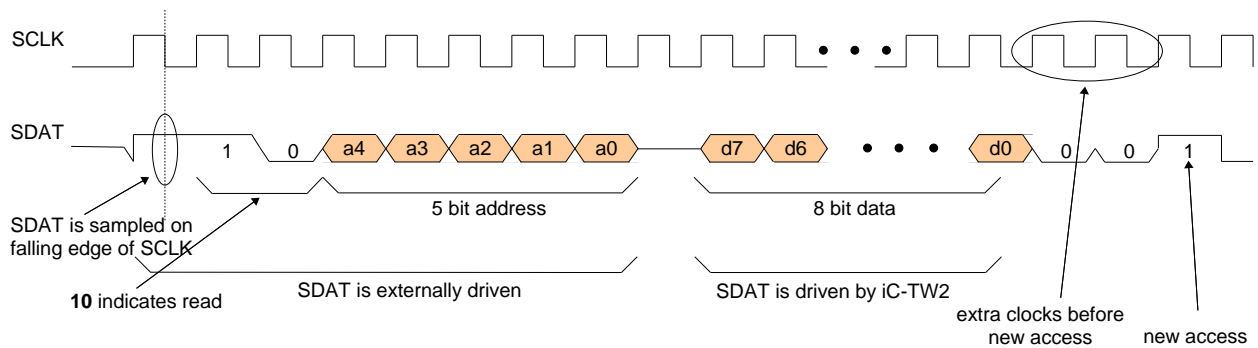


Figure 15: Register bank read access on 2-wire interface

Write access to the EEPROM follows the procedure depicted in Figure 16. A start bit is followed by four command bits c-1-e-b. The encoding of the command bits is shown in Table 31. The most useful command

is **0100** which performs an erase followed by a write therefore allowing the user to write a new value to the EEPROM with only one interface access.

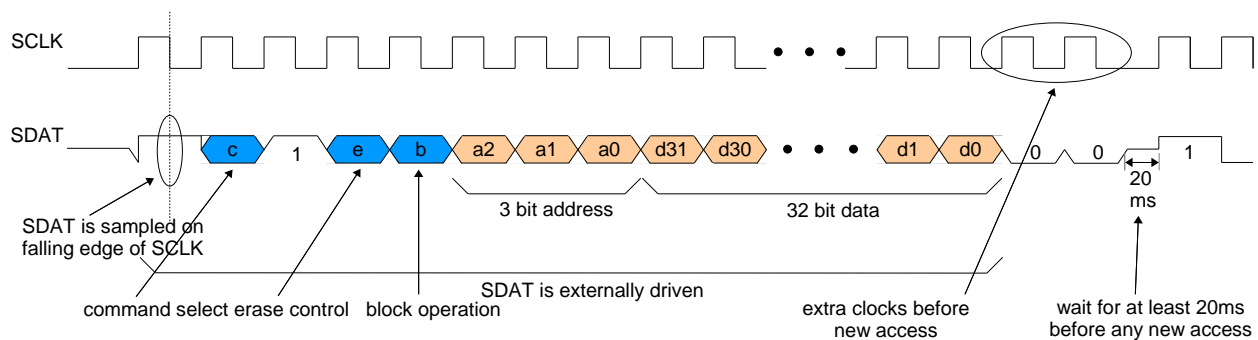


Figure 16: EEPROM write access on 2-wire interface

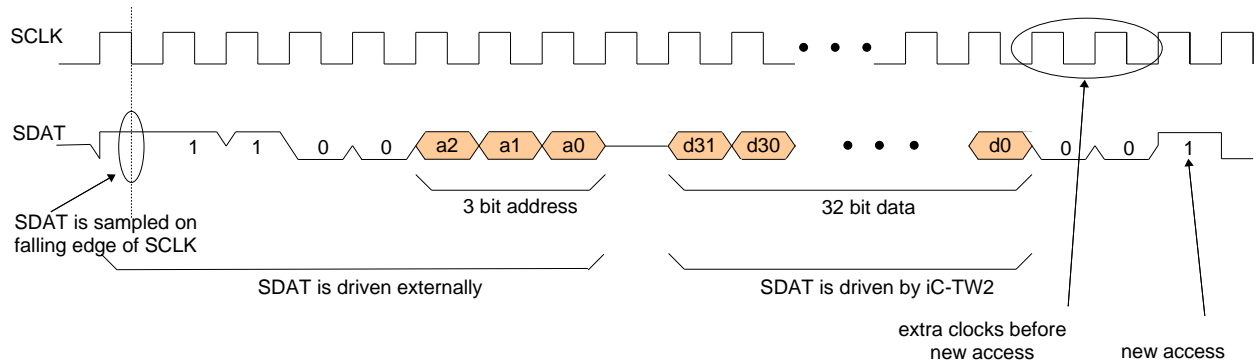


Figure 17: EEPROM read access on 2-wire interface

The 3 bit address $a(2:0)$ selects the EEPROM register to write to (Figure 13). Each EEPROM register is 32 bits wide, therefore 32 data bits $d(31:0)$ are sent across the interface. At least 20 ms delay is required after every transaction before any new access can start.

EEPROM read access is shown in Figure 17. The start bit is followed with the 4 bit read command **1100** and the 3 bit address $a(2:0)$. An idle clock cycle is used to avoid any contention on SDAT while reversing data flow direction. Finally $d(31:0)$ is shifted out on SDAT. EEPROM read access is slow.

At least one extra clock with SDAT low is required after every transaction on the 2-wire interface before a new access is started. The interface will not work correctly if this clock cycle is omitted.

Refer to Table 32 regarding timings requirements. Please note, given timing specifications scale with f_{osc} . For instance, with $f_{osc} = 22$ MHz timings are reduced by 10%.

EEPROM Commands					
c	1	e	b	Description	Purpose
0	1	0	0	Erase followed by write	Normal EEPROM programming
0	1	0	1	Block erase followed by block write	Test only
0	1	1	0	Write	Special production environment
0	1	1	1	Block write	Test only
1	1	0	0	Read. Please refer to Figure 17 for more details	
1	1	0	1	Reserved. Do not use this command	
1	1	1	0	Erase	Test only
1	1	1	1	Block erase	Special production environment

Table 31: EEPROM Commands

2W-Interface timing

The timing of the 2W-Interface is dependent on the type of access performed. Register bank access and EEPROM write access can be performed at full speed. EEPROM read access requires a slow SCLK. Also a 20 ms delay is required after every EEPROM write access before a new transaction of any kind is started (this includes read and write to the register bank).

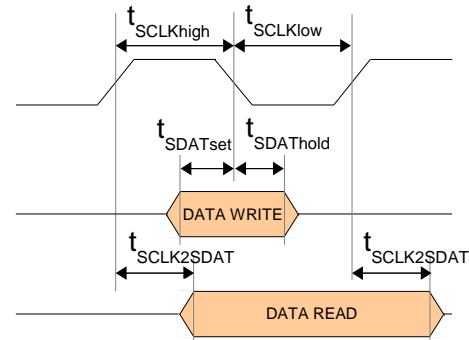


Figure 18: 2W-Interface timing diagram

2W-Interface timing				
Parameter	Description	Condition	min	max
t _{SCLKhigh}	SCLK high	EEPROM read access Any other access	8 μs 400 ns	
t _{SCLKlow}	SCLK low	EEPROM read access Any other access	8 μs 400 ns	
t _{SDATset}	SDAT setup before falling edge of SCLK	Write access	100 ns	
t _{SDATHold}	SDAT hold after falling edge of SCLK	Write access	100 ns	
t _{SCLK2SDAT}	SCLK to SDAT valid delay after rising edge of SCLK	EEPROM read access Any other access	5 ns 5 ns	7 μs 105 ns
Notes	Timings given above are valid for f _{osc} = 20 MHz and scale with f _{osc} . For instance, f _{osc} = 22 MHz reduces all given timings by 10%.			

Table 32: 2W-Interface timing

Trouble Shooting

To transfer iC-TW2's configuration data from RAM to EEPROM command EE_WRITE must be used.

Power must be available over the whole process taking approx. 100 ms. The suggested 1 μF bypass capacitors are important. GUI button <Read EEPROM> must deliver reliable contents.

To help iC-TW2's 2-wire interface not to receive disturbances, an external pull-down resistor at SCLK (e.g. 1 kΩ) may be used to support its internal pull-down keeping the idle state.

iC-TW2's interface does not feature a timeout, and there is no enable pin (as for SPI). A certain risk for losing the synchronisation does exist. For instance, connecting a programming cable may introduce edges to SCLK, so that the interface is not synchronized for communication anymore.

In case of communication problems try to reset iC-TW2 by pulling pin NRST low. When doing so, there should be no communication.

Another solution can be to clear the interface by applying approx. 50 clock pulses to SCLK while SDAT is held low.

1W-Interface

The 1W-Interface provides a write-only access port to the register bank. It is intended as a minimal configuration interface to program the internal EEPROM during in-field service or production. An infrared phototransistor can directly connect to the pin to build a cost effective wireless write port. The input bit stream is pulse-width modulated (or duty-cycle modulated) as

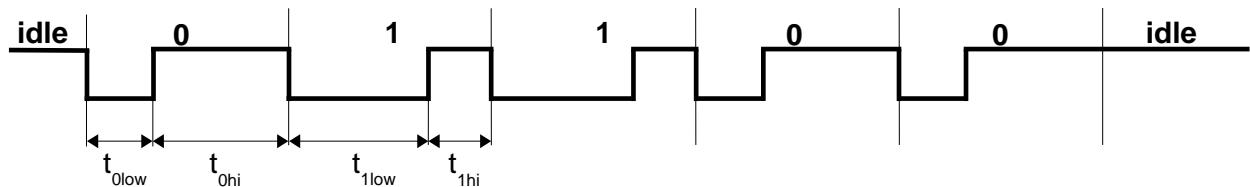


Figure 19: Pulse width modulated bit stream

The interface timing is specified in the following Table.

Parameter	Description	min	max
t_{0low}	Low time bit 0	40 μ s	100 μ s
t_{0hi}	High time bit 0	120 μ s	200 μ s
t_{1low}	Low time bit 1	120 μ s	200 μ s
t_{1high}	High time bit 1	40 μ s	100 μ s

Table 33: 1W-Interface timing

1W-Interface write sequence

Figure 20 describes the write sequence to the register bank, which uses the same protocol as the 2W-Interface. On an idle wire, a write sequence is initiated by writing a start bit (**1**) followed by the write command (**00**) followed by the address and register data. At the end of the sequence, a stop-bit (**0**) is required.

1W-Interface write access to the EEPROM bank is shown in Figure 21. The 4 bit EEPROM command after the start bit is decoded in Table 31.

Writing the register bank to the EEPROM

To permanently store a configuration in the internal EEPROM the following procedure should be followed.

1. The 1W-/2W-Interface is used to fully write the desired configuration into the register bank.
2. A logic one is written to bit EE_WRITE of register 0x0E. This will initiate a write sequence which copies all registers into the internal EEPROM. A complete write takes 100 ms. During this time, no access to the register bank through either the

shown in Figure 19. A zero-bit is encoded as a short low followed by a long high. A one-bit is encoded as a long low followed by a short high. The modulated signal is independent of the receiver or transmitter clock frequency. Since the iC-TW2 uses a free-running oscillator, it is important to implement a robust, frequency-insensitive protocol.

1W-/2W-Interface is allowed or data corruption might occur.

3. Finally the register content, after a device reset and configuration, should be verified to ensure a successful EEPROM write sequence.

Writing the registers to the EEPROM using EE_WRITE takes up to 100msec. During this access to the register bank either through the 1W- or 2W-Interface is prohibited. Any access will corrupt data written to the EEPROM.

EE_WRITE	Addr. 0x0E; bit 6	W
Code	Function, bit is automatically reset upon completion of operation	
0	Normal operation (default)	
1	Store registers into EEPROM	

Table 34: EEPROM store command

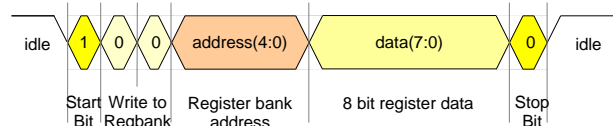


Figure 20: 1W-Interface register bank write sequence

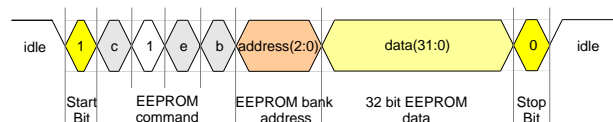


Figure 21: 1W-Interface EEPROM write sequence

TEST MODES

The iC-TW2 provides various control bits located in different registers to enable or disable certain test modes. The majority of these is only required for extended chip testing capability, others are required for production test.

GRANULAR		Addr. 0x05; bit 7	R/W
Code	Function, test mode only		
0	normal operation		
1	test mode only		

Table 35: A/B output edge granularity control

VC(1:0)		Addr. 0x0A; bit 6:5	R/W
Code	Function, test mode only		
	register must be set to 0 for correct device functionality		

Table 36: Reference voltage fine tuning

CLKMODE		Addr. 0x0B; bit 0	R/W
Code	Function, test mode only		
0	Select comparator clock <i>default</i>		
1	Select direct oscillator clock		

Table 37: Clock source select

CLKDLY		Addr. 0x0B; bit 2	R/W
Code	Function		
0	Normal operation		
1	Add clock delay		

Table 38: Clock distribution delay line selection

Enabling the position monitor will allow access to the internal absolute period position. The position can be read through register 0x0F. This is considered a test mode and should not be used during normal operation.

EN_MON		Addr. 0x0B; bit 3	R/W
Code	Function		
0	Position monitor disabled <i>default</i>		
1	Monitor enabled		

Table 39: Position monitor control

MONITOR(7:0)		Addr. 0x0F; bit 7:0	R/W
Code	Function		
	Access to the internal absolute period position. RT only!		

Table 40: Monitor register

EE_READ		Addr. 0x0E; bit 7	W
Code	Function		
0	Normal operation		
1	Read all iC-TW2 registers from the EEPROM. Bit is automatically reset upon completion. Not required during normal operation since this is done automatically on start-up.		

Table 41: EEPROM read command register

Production test control bits

Production test control bits are reserved bits. Do not use the production test control bits during normal operation. Keep reserved bits "0".

Reserved		Addr. 0xC; bit 7:1	R/W
Reserved		Addr. 0xD; bit 7:0	R/W
Reserved		Addr. 0xE; bit 2:0	R/W
Code	Function		
0	Normal operation		
1 ...	Do not use or alter to		

Table 42: Test modes

TYPICAL APPLICATIONS

The circuit in Figure 22 depicts a typical application. Differential sensor signals (or differential sine/cosine encoder signals) are directly connected to the iC-TW2.

Index gating is single ended active low as is frequently the case when using a Hall switch. The VC signal of 1.21 V is used to bias the positive input PINZ. It is recommended to decouple pin VC with a small capacitor when it is used as a reference. When pin VC is left unconnected, no capacitor is required.

Although iC-TW2 features internal pull-down current sources to define default pin levels, an additional pull-down resistor at pin SCLK can be recommended to reduce its disturbance and cross talk sensitivity.

When using pins NRST (low active reset input) and 1W (programming) is not intended, R1 and R2 can be replaced by shorts to VDD.

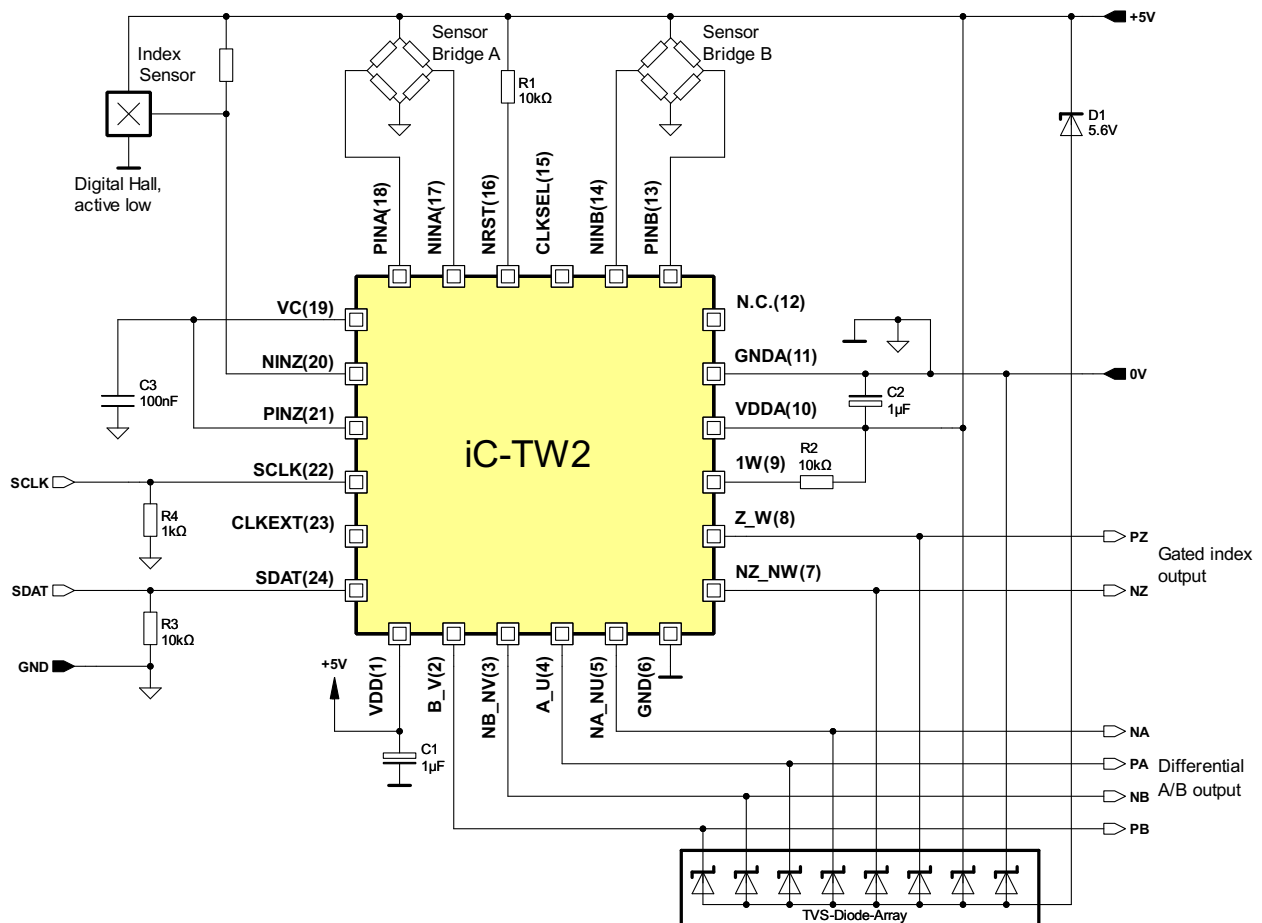


Figure 22: Application circuit with differential sin/cos sensor bridges and a Hall switch for index sensing.

PCB LAYOUT GUIDELINES

The iC-TW2 is a noise sensitive mixed signal device, which requires careful PCB layout considerations. Violating the layout guidelines can result in poor performance. Please consider Figure 23 .

Power pins VDDA (pin 10) and VDD (pin 1) must be decoupled with 1 μ F.

Trace length to VDD pins must be no longer than 3 mm.

The decoupling caps can be placed on the bottom side of the PCB directly connecting it to the iC-TW2 pads using vias.

Ground pins GND (pin 6) and GNDA (pin 11) must be tied to the center exposed pad.

The exposed pad is then directly connected to the PCB ground plane using several vias.

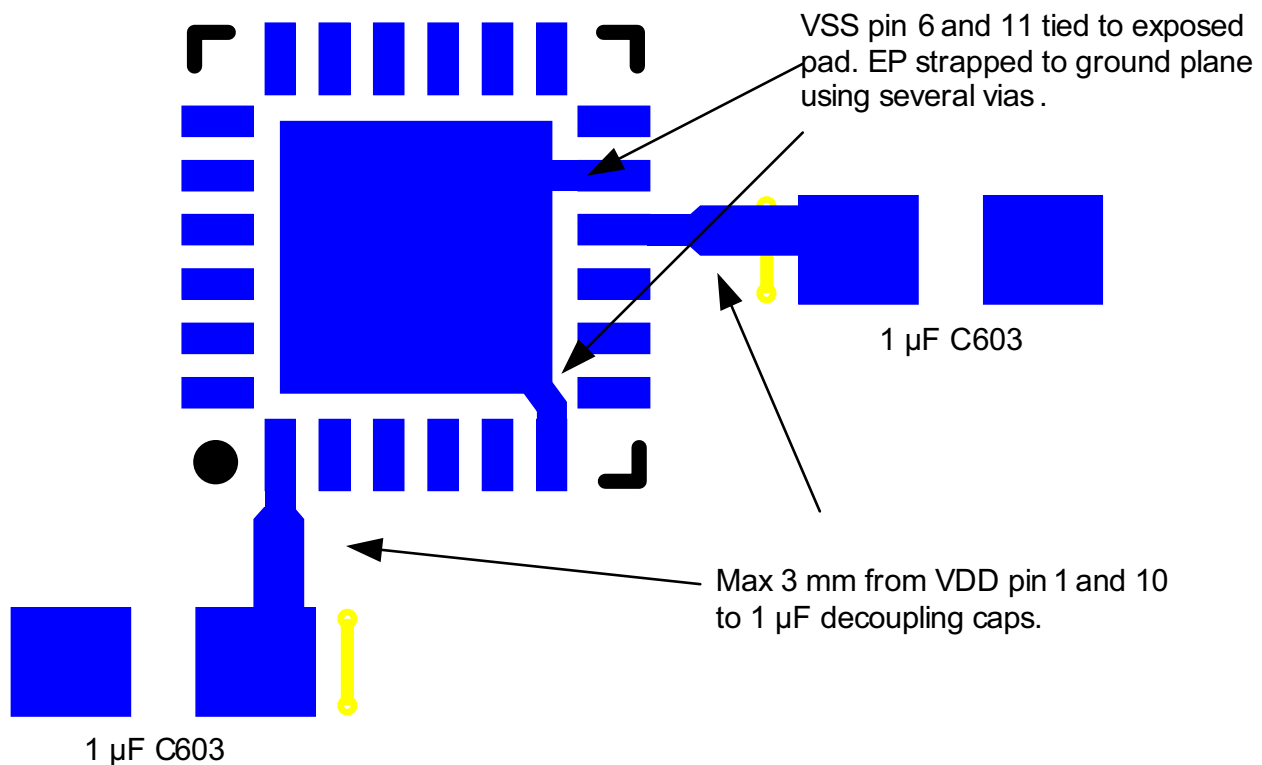


Figure 23: PCB layout guidelines

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iC-TW2 8-BIT SIN/COS INTERPOLATION IC WITH INTEGRATED EEPROM



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ORDERING INFORMATION

Type	Package	Order Designation
iC-TW2 Evaluation Board	24 pin QFN, 4 mm x 4 mm PCB 100 mm x 80 mm	iC-TW2 QFN24 iC-TW2 EVAL TW2_2D

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